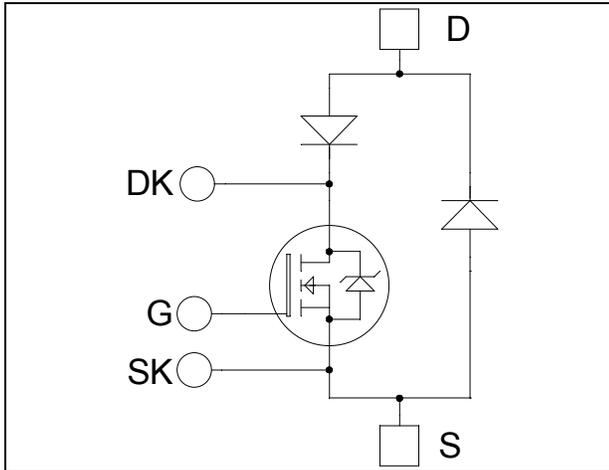


*Single switch
Series & SiC parallel diodes
MOSFET Power Module*

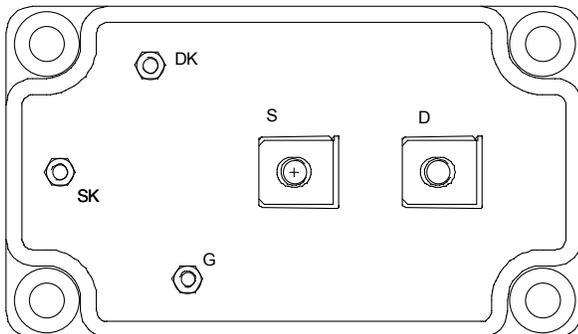
$V_{DSS} = 1000V$

$R_{DSon} = 65m\Omega$ typ @ $T_j = 25^\circ C$

$I_D = 145A$ @ $T_c = 25^\circ C$



G, SK and DK terminals are for control signals only
(not for power)



Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

Features

- **Power MOS 7[®] MOSFETs**
 - Low R_{DSon}
 - Low input and Miller capacitance
 - Low gate charge
 - Avalanche energy rated
 - Very rugged
- **SiC Parallel Schottky Diode**
 - Zero reverse recovery
 - Zero forward recovery
 - Temperature Independent switching behavior
 - Positive temperature coefficient on VF
- Kelvin source for easy drive
- Kelvin drain for voltage monitoring
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
 - M3 power connectors
- High level of integration
- AlN substrate for improved MOSFET thermal performance

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Low profile
- RoHS Compliant

All ratings @ $T_j = 25^\circ C$ unless otherwise specified

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

Absolute maximum ratings

| <i>Symbol</i> | <i>Parameter</i> | <i>Max ratings</i> | <i>Unit</i> |
|---------------------|---|-----------------------|-------------|
| V _{DSS} | Drain - Source Breakdown Voltage | 1000 | V |
| I _D | Continuous Drain Current | T _c = 25°C | 145 |
| | | T _c = 80°C | 110 |
| I _{DM} | Pulsed Drain current | 580 | A |
| V _{GS} | Gate - Source Voltage | ±30 | V |
| R _{DS(on)} | Drain - Source ON Resistance | 78 | mΩ |
| P _D | Maximum Power Dissipation | T _c = 25°C | 3250 |
| I _{AR} | Avalanche current (repetitive and non repetitive) | 30 | A |
| E _{AR} | Repetitive Avalanche Energy | 50 | mJ |
| E _{AS} | Single Pulse Avalanche Energy | 3200 | |

Electrical Characteristics

| <i>Symbol</i> | <i>Characteristic</i> | <i>Test Conditions</i> | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|---------------------|---------------------------------|---|------------------------|------------|------------|-------------|
| I _{DSS} | Zero Gate Voltage Drain Current | V _{GS} = 0V, V _{DS} = 1000V | T _j = 25°C | | 400 | μA |
| | | V _{GS} = 0V, V _{DS} = 800V | T _j = 125°C | | 2 | mA |
| R _{DS(on)} | Drain – Source on Resistance | V _{GS} = 10V, I _D = 72.5A | | 65 | 78 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} = V _{DS} , I _D = 20mA | 3 | | 5 | V |
| I _{GSS} | Gate – Source Leakage Current | V _{GS} = ±30 V, V _{DS} = 0V | | | ±400 | nA |

Dynamic Characteristics

| <i>Symbol</i> | <i>Characteristic</i> | <i>Test Conditions</i> | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|---------------------|------------------------------|---|------------|------------|------------|-------------|
| C _{iss} | Input Capacitance | V _{GS} = 0V V _{DS} = 25V f = 1MHz | | 28.5 | | nF |
| C _{oss} | Output Capacitance | | | 5.08 | | |
| C _{rss} | Reverse Transfer Capacitance | | | 0.9 | | |
| Q _g | Total gate Charge | V _{GS} = 10V V _{Bus} = 500V I _D = 145A | | 1068 | | nC |
| Q _{gs} | Gate – Source Charge | | | 136 | | |
| Q _{gd} | Gate – Drain Charge | | | 692 | | |
| T _{d(on)} | Turn-on Delay Time | V _{GS} = 15V V _{Bus} = 670V I _D = 145A R _G = 0.75Ω | | 18 | | ns |
| T _r | Rise Time | | | 14 | | |
| T _{d(off)} | Turn-off Delay Time | | | 140 | | |
| T _f | Fall Time | | | 55 | | |
| E _{on} | Turn-on Switching Energy | Inductive switching @ 25°C V _{GS} = 15V, V _{Bus} = 670V I _D = 145A, R _G = 0.75Ω | | 2.9 | | mJ |
| E _{off} | Turn-off Switching Energy | | | 2.9 | | |
| E _{on} | Turn-on Switching Energy | Inductive switching @ 125°C V _{GS} = 15V, V _{Bus} = 670V I _D = 145A, R _G = 0.75Ω | | 4.8 | | mJ |
| E _{off} | Turn-off Switching Energy | | | 3.9 | | |

Series diode ratings and characteristics

| <i>Symbol</i> | <i>Characteristic</i> | <i>Test Conditions</i> | | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|---------------|---|--|---------------------|------------|------------|------------|-------------|
| V_{RRM} | Maximum Peak Repetitive Reverse Voltage | | | 200 | | | V |
| I_{RM} | Maximum Reverse Leakage Current | $V_R=200V$ | $T_j = 25^\circ C$ | | | 350 | μA |
| | | | $T_j = 125^\circ C$ | | | 600 | |
| I_F | DC Forward Current | $T_c = 80^\circ C$ | | | 120 | | A |
| V_F | Diode Forward Voltage | $I_F = 120A$ | | | 1.1 | 1.15 | V |
| | | $I_F = 240A$ | | | 1.4 | | |
| | | $I_F = 120A$ | $T_j = 125^\circ C$ | | 0.9 | | |
| t_{rr} | Reverse Recovery Time | $I_F = 120A$ $V_R = 133V$ $di/dt = 400A/\mu s$ | $T_j = 25^\circ C$ | | 31 | | ns |
| | | | $T_j = 125^\circ C$ | | 60 | | |
| Q_{rr} | Reverse Recovery Charge | $I_F = 120A$ $V_R = 133V$ $di/dt = 400A/\mu s$ | $T_j = 25^\circ C$ | | 120 | | nC |
| | | | $T_j = 125^\circ C$ | | 500 | | |

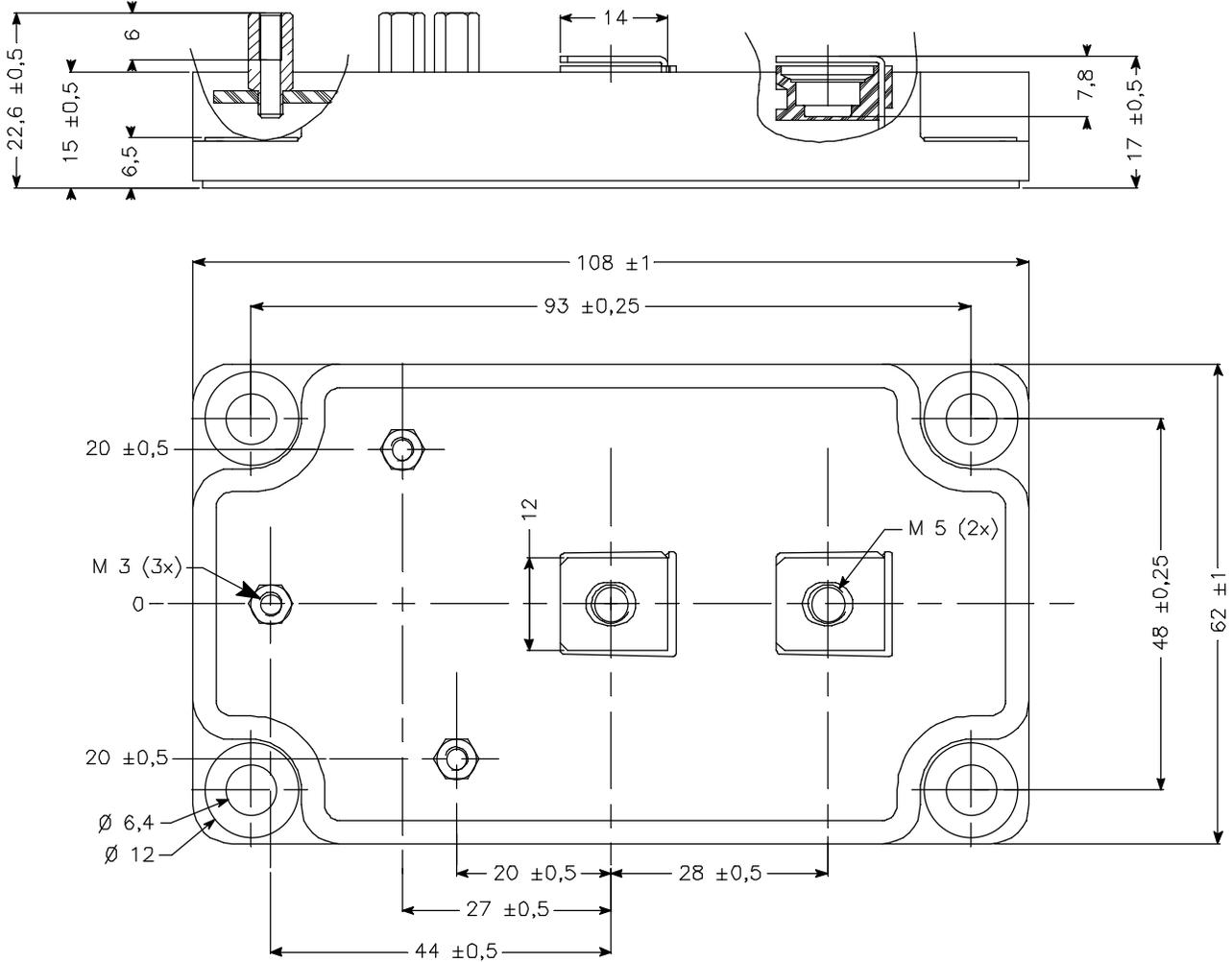
SiC Parallel diode ratings and characteristics

| <i>Symbol</i> | <i>Characteristic</i> | <i>Test Conditions</i> | | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|---------------|---|---|---------------------|------------|------------|------------|-------------|
| V_{RRM} | Maximum Peak Repetitive Reverse Voltage | | | 1200 | | | V |
| I_{RM} | Maximum Reverse Leakage Current | $V_R=1200V$ | $T_j = 25^\circ C$ | | 384 | 2400 | μA |
| | | | $T_j = 125^\circ C$ | | 672 | 12000 | |
| I_F | DC Forward Current | $T_c = 125^\circ C$ | | | 120 | | A |
| V_F | Diode Forward Voltage | $I_F = 120A$ | $T_j = 25^\circ C$ | | 1.6 | 1.8 | V |
| | | | $T_j = 175^\circ C$ | | 2.3 | 3.0 | |
| Q_C | Total Capacitive Charge | $I_F = 120A, V_R = 600V$ $di/dt = 5000A/\mu s$ | | | 480 | | nC |
| C | Total Capacitance | $f = 1MHz, V_R = 200V$ | | | 1152 | | pF |
| | | $f = 1MHz, V_R = 400V$ | | | 828 | | |

Thermal and package characteristics

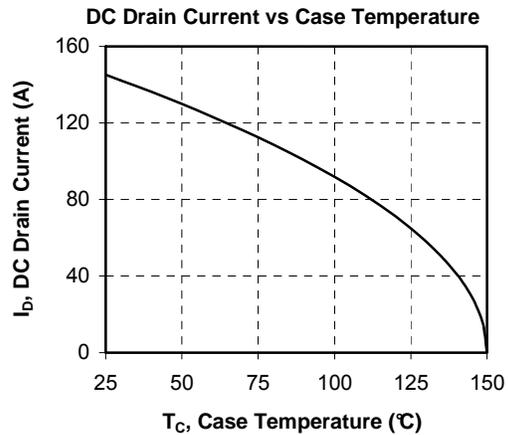
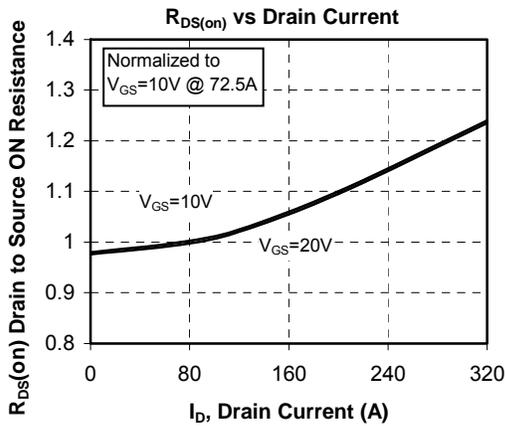
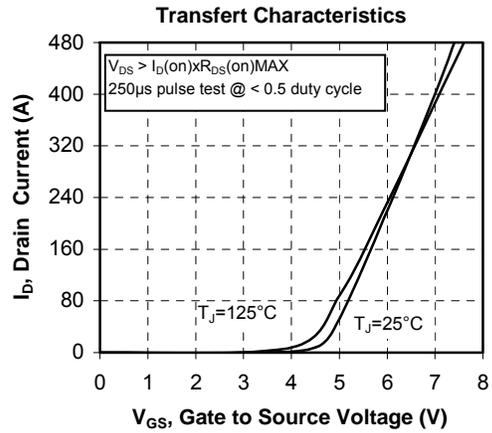
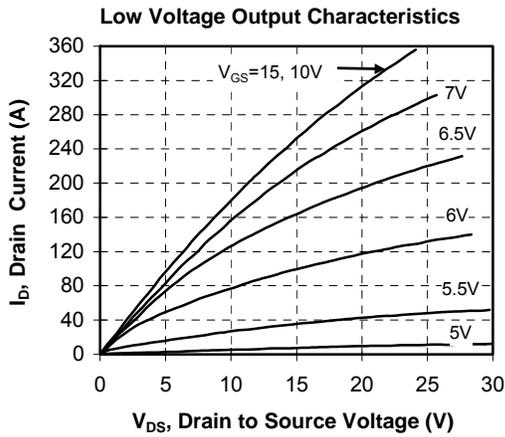
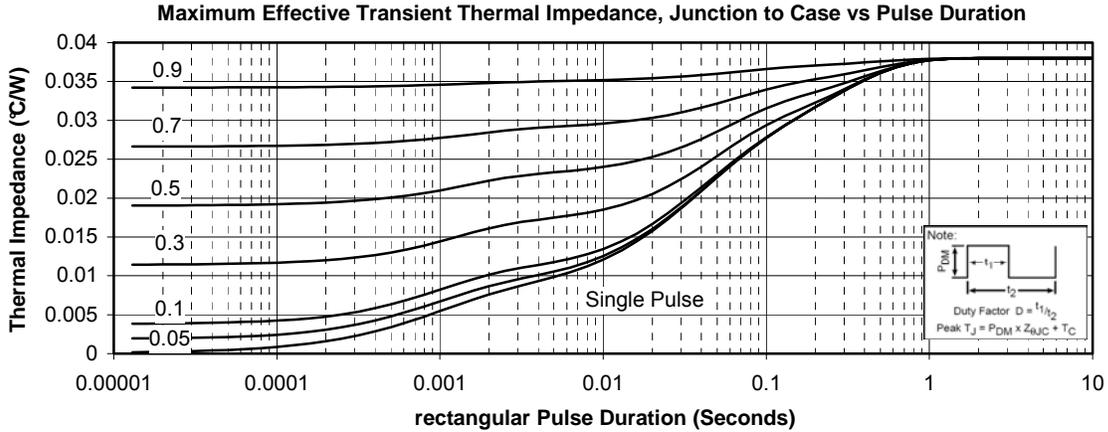
| <i>Symbol</i> | <i>Characteristic</i> | | | <i>Min</i> | <i>Typ</i> | <i>Max</i> | <i>Unit</i> |
|---------------|--|--------------------|----|------------|------------|------------|--------------|
| R_{thJC} | Junction to Case Thermal Resistance | Transistor | | | | 0.038 | $^\circ C/W$ |
| | | Series diode | | | | 0.46 | |
| | | SiC Parallel diode | | | | 0.18 | |
| V_{ISOL} | RMS Isolation Voltage, any terminal to case $t=1$ min, $I_{isol}<1mA, 50/60Hz$ | | | 4000 | | | V |
| T_J | Operating junction temperature range | | | -40 | | 150 | $^\circ C$ |
| T_{STG} | Storage Temperature Range | | | -40 | | 125 | |
| T_C | Operating Case Temperature | | | -40 | | 100 | |
| Torque | Mounting torque | To heatsink | M6 | 3 | | 5 | N.m |
| | | For terminals | M5 | 2 | | 3.5 | |
| | | | M3 | 1 | | 1.5 | |
| Wt | Package Weight | | | | | 280 | g |

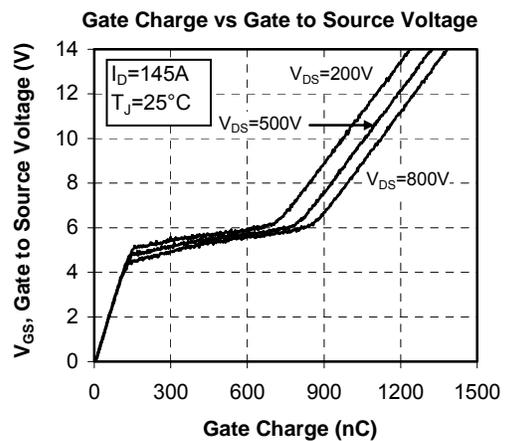
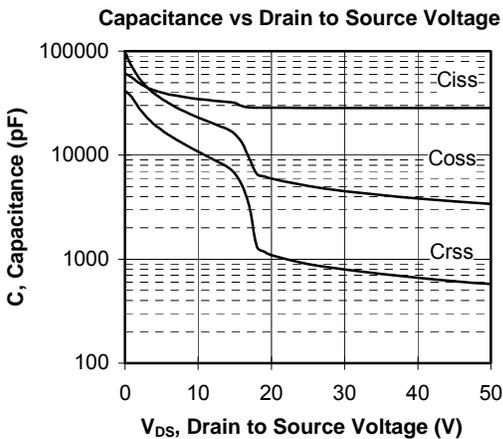
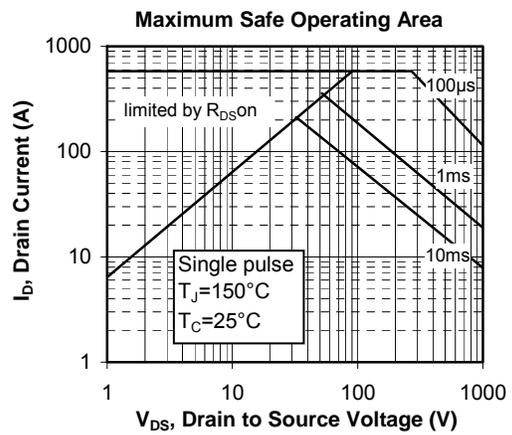
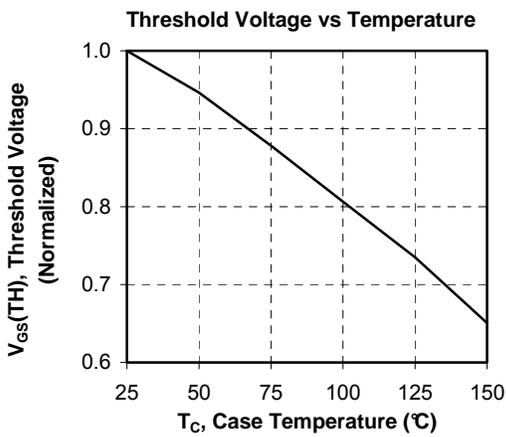
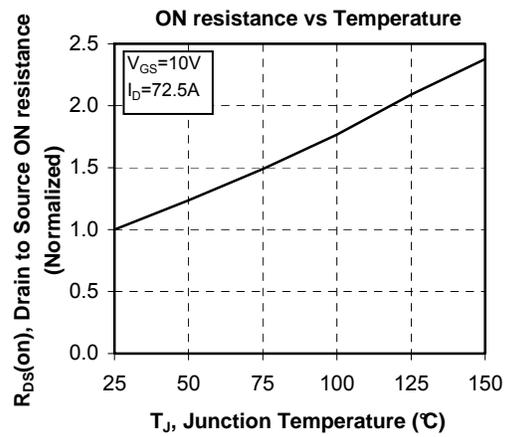
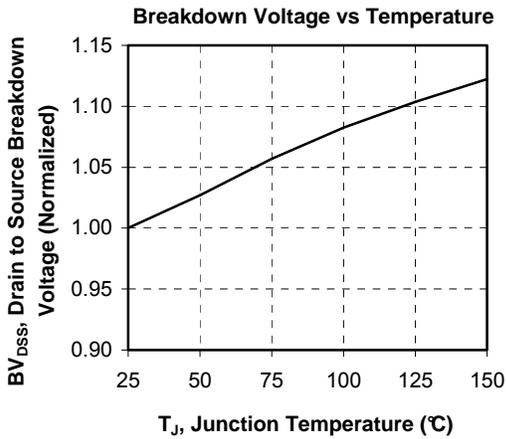
SP6 Package outline (dimensions in mm)

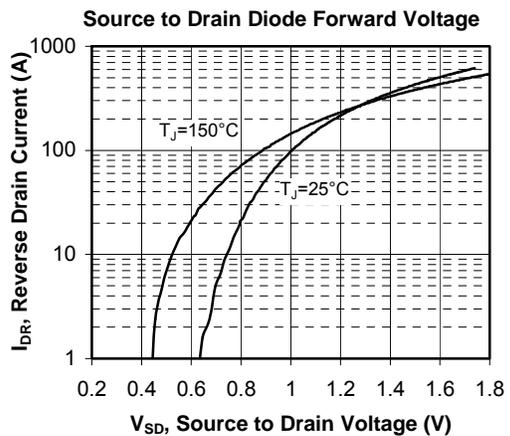
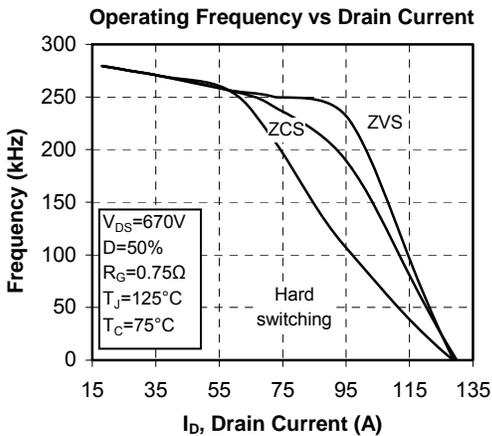
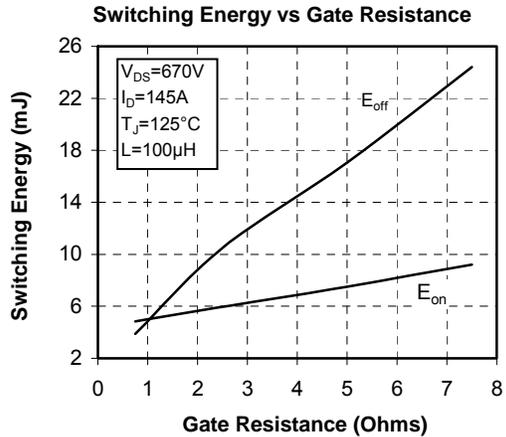
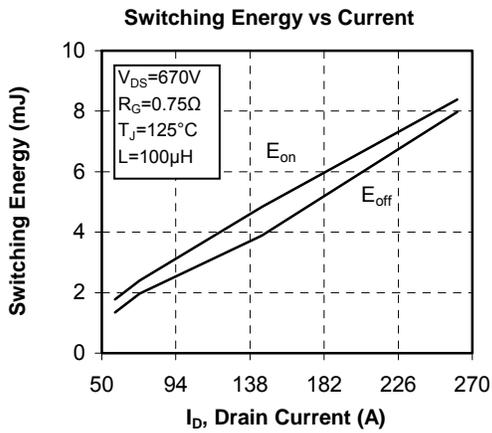
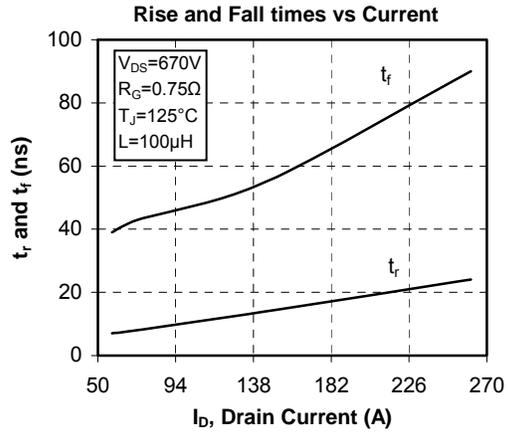
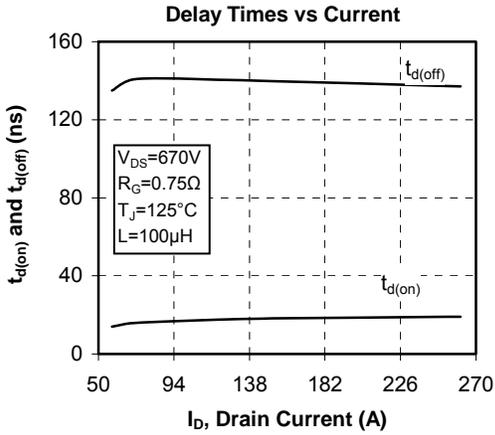


See application note APT0601 - Mounting Instructions for SP6 Power Modules on www.microsemi.com

Typical MOSFET Performance Curve

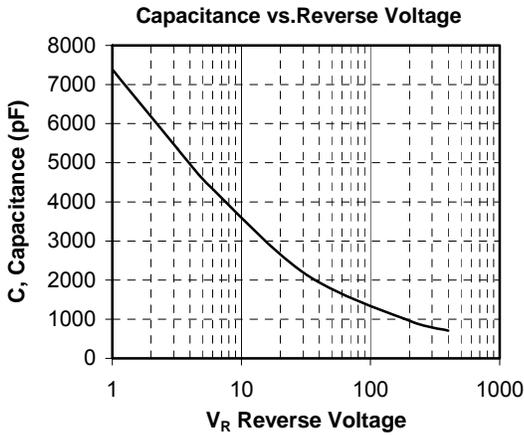
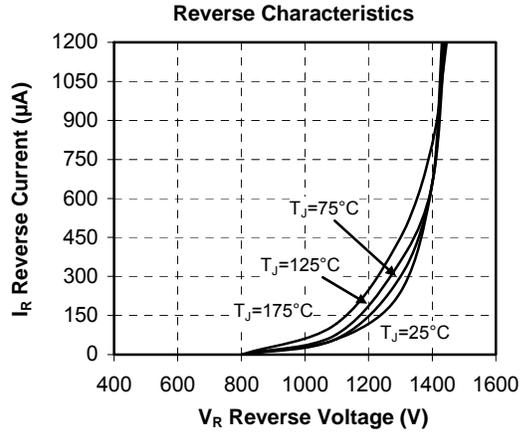
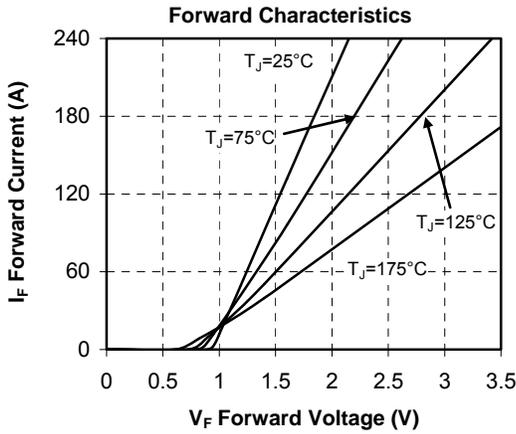
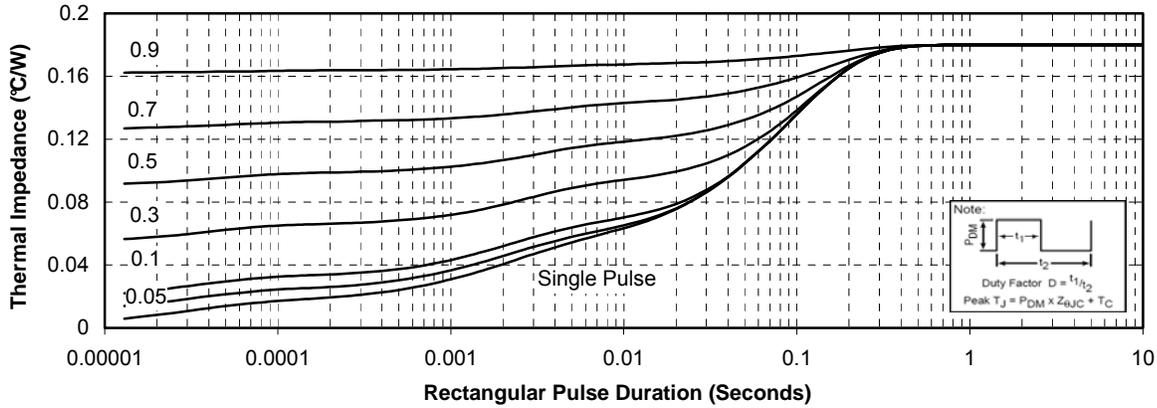






Typical SiC Diode Performance Curve

Maximum Effective Transient Thermal Impedance, Junction to Case vs Pulse Duration



Microsemi reserves the right to change, without notice, the specifications and information contained herein

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